



Material Content Data Sheet



Sales Product Name	TLE4207G			Issued		28. August 2013		
MA#	MA000982426							
Package	PG-DSO-14-22			Weight*		142.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.947	2.06	2.06	20613	20613
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		106	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8443	
	non noble metal	copper	7440-50-8	49.007	34.28	35.17	342826	351797
wire	noble metal	gold	7440-57-5	0.273	0.19	0.19	1913	1913
encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1209	
	plastics	epoxy resin	-	7.948	5.56		55600	
	inorganic material	silicondioxide	60676-86-0	78.271	54.77	60.45	547544	604353
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8577	8577
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7204	7204
glue	plastics	acrylic resin	-	0.174	0.12		1219	
	noble metal	silver	7440-22-4	0.618	0.43	0.55	4324	5543
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

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